



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C16M16MSA-6BIN								
Part Weight:		101.167mg								
NO.	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	G1250	57.595	Epoxy Resin	Resin		5.50%	3.168	3.1312%	31,312
				Phenol resin	Resin		4.50%	2.592	2.5619%	25,619
				Silica(Fused)	filler	60676-86-0	89.70%	51.663	51.0668%	510,668
				Carbon Black	Additive	1333-86-4	0.30%	0.173	0.1708%	1,708
2	Substrate	BT	28.815	832NX-A	BT core		46.13%	13.292	13.1390%	131,390
				AUS308	Solder Mask		13.75%	3.962	3.9164%	39,164
				Cu	Trace	7440-50-8	39.37%	11.344	11.2136%	112,136
				Ni	Plating	7440-02-0	0.66%	0.190	0.1880%	1,880
				Au	Plating	7440-57-5	0.09%	0.026	0.0256%	256
3	DAF	EM700	0.577	Solid Epoxy Resin	Base material		12.50%	0.072	0.0713%	713
				Phenol Resin	Base material		12.50%	0.072	0.0713%	713
				Fused Silica	Base material	60676860	35.00%	0.202	0.1996%	1,996
				Synthrtic Rubber	Base material		40.00%	0.231	0.2281%	2,281
4	Wire	AG0B	0.467	Ag	Base material	7440-22-4	89.10%	0.416	0.4113%	4,113
				Au	Base material	7440-57-5	7.40%	0.035	0.0342%	342
				Pd	Base material	7440/5/3	3.50%	0.016	0.0162%	162
5	Solder Ball	M705	8.971	Tin (Sn)	Base material	7440-31-5	96.50%	8.657	8.5572%	85,572
				Ag	Base material	7440-22-4	3.00%	0.269	0.2660%	2,660
				Cu	Base material	7440-50-8	0.50%	0.045	0.0443%	443
6	Die	0.12mm	4.742	Si	Chip	7440-21-3	100.00%	4.742	4.6873%	46,873
								101.167	100%	1,000,000